

# DATA SHEET

SURFACE-MOUNT CERAMIC MULTILAYER CAPACITORS C-Array: Class 1, NPO 50 V

size 0508 (4 × 0402)



### Phicomp

#### Product specification

### C-Array: Class 1, NP0 50 V size 0508 (4 × 0402)

### FEATURES

- 4 × 0402 capacitors (of the same capacitance value) per array
- Less than 50% board space of an equivalent discrete component
- High volumetric efficiency
- Dense dielectric layers
- Supplied in tape on reel or loose in bag
- Increased throughput by time saved in mounting
- Cost savings on manufacturing time.

#### **APPLICATIONS**

- Professional electronics
- High density consumer electronics
- Automotive.

#### DESCRIPTION

Each capacitor element consists of a rectangular block of ceramic dielectric in which a number of interleaved precious metal electrodes are contained. This structure gives rise to a high capacitance per unit volume.

The inner electrodes are connected to the two terminations, silver dipped with a barrier layer of plated nickel and finally covered with a layer of plated tin (NiSn). An outline of the structure is shown in Fig.1.

#### QUICK REFERENCE DATA

DESCRIPTION	VALUE
Rated voltage U <sub>R</sub> (DC)	50 V
Capacitance range (E12 series)	10 pF to 270 pF
Tolerance on capacitance	±5%, ±10%
Test voltage (DC) for 1 minute	$2.5  imes U_R$
Sectional specifications	IEC 60384-10, second edition 1989-04; also based on CECC 32 100
Detailed specification	based on CECC 32 101-801
Climatic category (IEC 60068)	55/125/56



### C-Array: Class 1, NP0 50 V size 0508 (4 × 0402)

### **MECHANICAL DATA**



#### **Physical dimensions**

 Table 1
 Capacitor dimensions for product size 0508 (4 × 0402)

CASE SIZE	L	W	Т	Α	В	Р
Dimensions in	millimetres					
0508 (4 × 0402)	2.0 ±0.15	1.25 ±0.15	0.60 ±0.10	0.28 ±0.10	0.2 ±0.10	0.50 ±0.10

### C-Array: Class 1, NP0 50 V size 0508 (4 × 0402)

### DIMENSIONS OF SOLDER LANDS



#### Table 2 Solder land dimensions; see Fig.3

CASE SIZE	FOOTPRINT DIMENSIONS (mm)			
	Α	В	Р	Е
0508 (4 × 0402)	2.0 +0.40/-0.20	0.31 ±0.10	0.50±0.10	0.30 +0.02/-0.05

### C-Array: Class 1, NP0 50 V size 0508 (4 × 0402)

C LAST 1	LAST TWO	50 V
(pF)	F) DIGITS OF 12NC	0508 (4 × 0402)
10	23	
12	24	
15	25	
18	26	
22	27	
27	28	
33	29	
39	31	
47	32	0.6 ±0.1
56	33	
68	34	
82	35	
100	36	
120	37	
150	38	
180	39	
220	41	
270	42	

### **SELECTION CHART FOR 50 V**

### Note

1. Values in shaded cells indicate thickness class.

### Thickness classification and packing quantities

THICKNESS	8 mm TAPE WIDTH QUANTITY PER REEL	
CLASSIFICATION (mm)	Ø180 mm; 7"	
	PAPER	
0.6 ±0.1	4 000	

### C-Array: Class 1, NP0 50 V size 0508 (4 × 0402)

### **ORDERING INFORMATION**

Components may be ordered by using either a Phycomp's unique 12NC or simple 15-digit clear text code.

### Ordering code 12NC (preferred)



#### Clear text code

EXAMPLE: 0508CG820J9B100

Size Code	Temp. Char.	Capacitance	Tol.	Vol.	Termination	Packing	Marking	Series
0508 (4 × 0402)	CG = NP0	820 = 82  pF; the third digit signifies the multiplying factor: $0 = \times 1$ $1 = \times 10$	J = ±5% K = ±10%	9 = 50 V	B = NiSn	2 = 180 mm; 7" paper	0 = no marking	0 = conv. ceramic

### C-Array: Class 1, NP0 50 V size 0508 (4 × 0402)

### **ELECTRICAL CHARACTERISTICS**

### Class 1 capacitors; NP0 dielectric; NiSn terminations

Unless otherwise stated all electrical values apply at an ambient temperature of 20  $\pm$ 1 °C, an atmospheric pressure of 86 to 106 kPa, and a relative humidity of 63 to 67%.

DESCRIPTION	VALUE
Capacitance range (E12 series); note 1	10 pF to 270 pF
Tolerance on capacitance after 1000 hours	±5%; ±10%
Test voltage (DC) for 1 minute	$2.5 \times U_R$
Tan δ; note 1	≤ 0.1%
Insulation resistance after 1 minute at U <sub>R</sub> (DC):	R <sub>ins</sub> ≥100 GΩ
Temperature coefficient	$(0 \pm 30) \times 10^{-6}/K$
Resistance to soldering heat	260 °C; 10 seconds

Note

1. Measured at 1 V, 1 MHz 20 °C, using a four-gauge method.

### C-Array: Class 1, NP0 50 V size 0508 (4 × 0402)



### C-Array: Class 1, NP0 50 V size 0508 (4 × 0402)

### TESTS AND REQUIREMENTS

Table 3	Test procedures and requirements
---------	----------------------------------

IEC 60384-10/ CECC 32 100 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS
4.5		visual inspection and dimension check	any applicable method using ×10 magnification	in accordance with specification
4.6.1		capacitance	f = 1 MHz; measuring voltage 1 V <sub>rms</sub> at 20 °C	within specified tolerance
4.6.2		tan $\delta$	f = 1 MHz; measuring voltage 1 V <sub>rms</sub> at 20 °C	in accordance with specification
4.6.3		insulation resistance	at U <sub>R</sub> (DC) for 1 minute	in accordance with specification
4.6.4		voltage proof	$2.5 \times U_R$ for 1 minute	no breakdown or flashover
4.7.1		temperature coefficient	between minimum and maximum temperature	in accordance with specification
4.8		adhesion	a force of 5 N applied for 10 s to the line joining the terminations and in a plane parallel to the substrate	no visible damage
4.9		bond strength of plating on end face	mounted in accordance with CECC 32 100, paragraph 4.4	no visible damage
			conditions: bending 1 mm at a rate of 1 mm/s, radius jig 340 mm	Δ <b>C/C:</b> ±10%
4.10	ТЬ	resistance to soldering heat; jig clamps to the second component along the longitudinal direction	270 $\pm$ 5 °C for 10 $\pm$ 0.5 s in a static solder bath	the terminations shall be well tinned after recovery $\Delta$ C/C: within ±0.5% or 0.5 pF, whichever is greater
		resistance to soldering heat; jig clamps to the second component along the longitudinal direction	260 $\pm$ 5 °C for 30 $\pm$ 1 s in a static solder bath	using visual enlargement of ×10, dissolution of the terminations shall not exceed 10%
4.11	Та	solderability; jig clamps to the second component along the longitudinal direction	zero hour test, and test after storage (20 to 24 months) in original packing in normal atmosphere; unmounted chips completely immersed for $3 \pm 0.5$ s in a solder bath at 215 $\pm$ 5 °C	the terminations shall be well tinned

### C-Array: Class 1, NP0 50 V size 0508 (4 × 0402)

IEC 60384-10/ CECC 32 100 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS
4.12	Na	rapid change of temperature	–55 °C to +125 °C; 5 cycles	no visible damage after 24 hours recovery; ∆C/C: within ±1% or 1 pF
4.14	Са	damp heat	56 days at 40 °C; 90 to 95% RH; U <sub>R</sub> applied	no visible damage after 24 hours recovery:
				$\Delta$ C/C: within ±2% or 1 pF, whichever is greater
				tan $\delta$ : 2 ×specified value
				$R_{ins}$ : 2500 $M\Omega$ or $R_iC_R \ge$ 25 s, whichever is less
4.15		endurance	1000 hours at maximum	after 24 hours recovery:
	temperature at $2 \times U_R$	temperature at $2 \times U_R$	$\Delta$ C/C: within ±2% or 1 pF, whichever is greater	
				tan $\delta$ : 2 xspecified value
				$R_{ins}$ : 4000 $M\Omega$ or $R_iC_R \geq$ 40 s,
				whichever is less

### C-Array: Class 1, NP0 50 V size 0508 (4 × 0402)

### **REVISION HISTORY**

Revision	Date	Change Notification	Description
Rev.4	2001 May 30	-	- Converted to Phycomp brand
Rev.5	2003 Mar 13	-	- Updated company logo
Rev.6	2003 Jul 18	-	- Cover page revised
Rev.7	2003 Oct 29	-	- Physical dimension revised on size B